

**LEAD FRAME FOR SEMICONDUCTOR DEVICE**

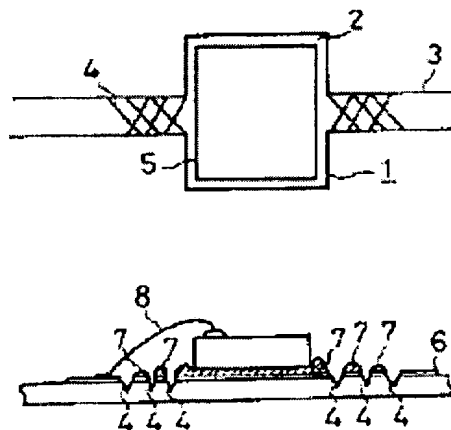
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**Abstract of JP4199557**

**PURPOSE:**To surely stop the flow of solder material by forming a plurality of parallel or crossed grooves for outflow prevention of solder material at the surface extremely near to the root of the die-pad part of a support bar.

**CONSTITUTION:**Plating layers 6 are formed at the die-pad part 2 of a lead frame 1 and in the vicinity of the die-pad part 2 of a support bar 3, which connects the die-pad part 2, and then grooves 4 for outflow prevention of solder material 7 are formed at the surface near the root of the die-pad part 2. As a result, the plated metal at the groove processed part is excluded, and also the plating remaining part, left at the plane between the crossed grooves, is more excellent in the wettability to the solder material 7, which has fused and diffused, than the groove parts 4, so the solder material becomes easy to stand at the plane parts between grooves, being caught there. Hereby, the flow of the solder material can be stopped surely.



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